



Material Content Data Sheet



Sales Product Name		TLE7259-3LE		Issued		25. January 2018		
MA#		MA001102860						
Package		PG-TSON-8-1		Weight*		27.00 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.290	4.78	4.78	47774	47774
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		109	
	non noble metal	zinc	7440-66-6	0.012	0.04		437	
	non noble metal	iron	7439-89-6	0.236	0.87		8746	
wire	non noble metal	copper	7440-50-8	9.586	35.51	36.43	355106	364398
	non noble metal	copper	7440-50-8	0.043	0.16	0.16	1588	1588
	encapsulation	organic material	carbon black	1333-86-4	0.030	0.11		1099
plastics	plastics	epoxy resin	-	1.528	5.66		56596	
	inorganic material	silicondioxide	60676-86-0	13.275	49.19	54.96	491782	549477
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14158	14158
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1610	1610
glue	plastics	epoxy resin	-	0.142	0.52		5249	
	noble metal	silver	7440-22-4	0.425	1.57	2.09	15746	20995
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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